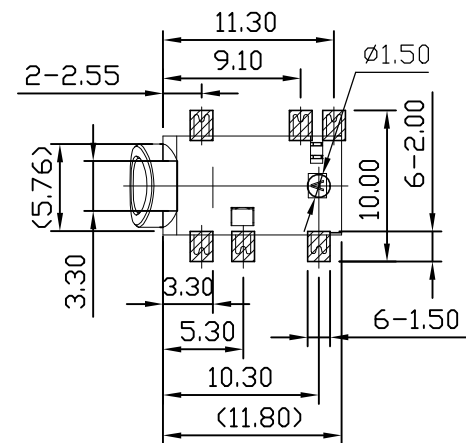
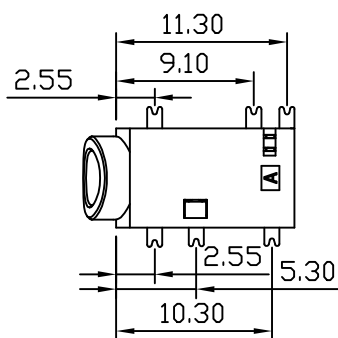
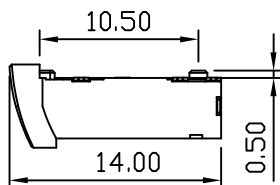
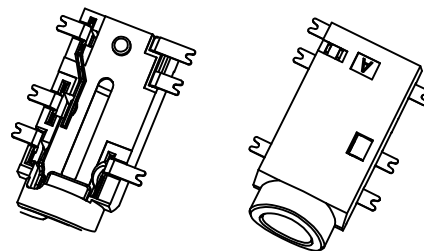




RIGHT PACKING P.C.B LAYOUT
TOP VIEW



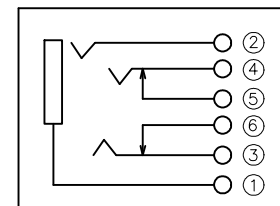
本公司智慧财产未经许可不得复制
ming biao copyright,may not be used without permission from ming biao.



3D VIEW



ALL SOLDER TAILS



CIRCUIT

技术要求:

1. 参照产品规范GWS-098, 电气及机械特性要求如下:
 - 1.1 接触阻抗: $50\text{m}\Omega$ 以下;
 - 1.2 绝缘阻抗: $100\text{M}\Omega$ 以上;
 - 1.3 耐电压: 500V AC 以上;
 - 1.4 耐插拔: 5,000次以上;
 - 1.5 插入力: $0.3\sim 3.0\text{kgf}(3\sim 30\text{N})$;
 - 1.6 拔出力: $0.3\sim 3.0\text{kgf}(3\sim 30\text{N})$;
2. 除特殊说明外, 无标示的尺寸均为参考尺寸;
3. 产品符合RoHS&HF环保标准要求.

  				 东莞市铭标电子科技有限公司 Ming Biao Electronic Technology Co., Ltd.				
TOLERANCE				DESIGN	DATE	TITLE	Ø3.5 PHONE JACK	
UNLESS OTHERWISE STATED				WJF	2024. 09. 24			
X.X	±0.20	SIZE	A4	CHKD	DATE	MODEL	ST-345-S	
X.XX	±0.15	REV	A					
X.XXX	±0.10	UNIT	mm	APPD	DATE	SHEET	1/3	
	±2°	SCALE	2:1			PRINT DATE	2025.07.07	